


Customer Product/Process Change Notice

No.	PCN02542	PCN Date	3/15/2013	Effective Date	6/15/2013
Title	Add TICP as a qualified source of the 16Mb X8 in the TSOP2 package				

Approval Notice		
Everspin Inc. will consider this change accepted unless specific conditions for acceptance are provided in writing within 30 days of receipt of this notice.		
Description and Purpose – Affected Products		
To increase production capacity and improve flexibility in manufacturing Everspin has qualified the following products to be manufactured at Taiwan IC Packaging Corp. (TICP) :		
Configuration	Everspin Part Numbers	Package
16Mb Toggle MRAM (2Mb x 8)	MR4A08BYS35,MR4A08BCYS35 (Includes R suffix for part numbers shipping in Tape and Reel.)	44 pin TSOP2
Material Differences		
TICP uses 0.8mil Pd-Cu bond wire.		
There is no effect on form, fit or function for products manufactured at TICP. There is no change for testing of these products.		
The assembly location symbol for TICP is W.		
Contact Information	Sample Information	
Joe O'Hare Director, Product Marketing Everspin Technologies joe.ohare@everspin.com 480-347-1099	Samples are available now Contact Everspin sales: http://everspin.com/contactus.php If using the on-line sample request please refer to this PCN #	
Originator		
<u>Date</u> 3/11/2013	<u>Title</u> VP Marketing	<u>Name</u> Steffen Hellmold 
Approval and Release		
<u>Date</u> 3/11/2013	<u>Title</u> VP Quality	<u>Name</u> Brad Engel 